

07-24-2007



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To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof.

1. Name of Conveying Party(ies):

**GENG-SHIN SHEN, AND  
WU-CHANG TU**

Additional names of conveying parties attached:  Yes  No

3. Nature of Conveyance:

- Assignment  Merger
- Security Agreement  Change of Name
- Other:

Execution Date: **June 22, 2007**

2. Name and Address of Receiving Party(ies):

Name: **Chipmos Technologies Inc.**  
Address: **No. 1, R&D Rd. 1, Science-Based  
Industrial Park**  
City: **Hsinchu  
Taiwan, R.O.C.**

and

Name: **Chipmos Technologies (Bermuda) Ltd.**  
Address: **Canon's Court, 22 Victoria Street**  
City: **Hamilton HM 12  
Bermuda**

4. (a) Patent Application Number(s):

If this document is being filed together with a new application,  
the execution date of the application is:

Additional Numbers Attached.

4. (b) Patent Numbers:

5. Name and Address of Party to whom Correspondence  
Concerning this Document Should be Mailed:

Name: **Stanley P. Fisher**  
  
Address: **Reed Smith LLP  
3110 Fairview Park Dr.  
Suite 1400  
Falls Church, VA 22042**

6. Total Number of Applications and Patents Involved: 1

7. Total Fee: **\$40.00**  
(37 C.F.R. § 3.41)

- Enclosed.
- Authorized to be charged to deposit account.

8. Deposit Account Number: **08-1480**

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9. Statement and Signature:

*To the best of my knowledge and belief, the foregoing is true and correct and any attached copy is a true copy of the original document.*

Stanley P. Fisher, Registration No. 24, 344

**July 16, 2007**  
  
Juan Carlos A. Marquez, Registration No. 34,072

Total number of pages comprising cover sheet: 1

07/17/2007 SZEWDIE1 0000052 11826516  
US FC:8021

40.00 OP

### ASSIGNMENT

WHEREAS, SHEN, GENG-SHIN, TU, WU-CHANG, whose post office addresses appear below hereinafter referred to as ASSIGNOR), have invented certain new and useful improvements in Stacked Chip Package Structure with Leadframe Having Inner Leads with Transfer Pad (hereinafter referred to as THE INVENTION) for which an application for United States Letters Patent was filed on \_\_\_\_\_, Application Number \_\_\_\_\_;

WHEREAS CHIPMOS TECHNOLOGIES INC. CHIPMOS TECHNOLOGIES (BERMUDA) LTD., whose post office address is No.1, R&D Rd.1, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C., Canon's Court, 22 Victoria Street, Hamilton HM 12, Bermuda(hereinafter referred to as ASSIGNEE), is desirous of acquiring the entire right, title and interest in and to the same in the United States and throughout the world;

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, we, ASSIGNOR, by these presents do sell, assign and transfer until said ASSIGNEE, the entire right, title and interest in and to said invention and application throughout the United States of America, including any and all United States Letters Patent granted on any division, continuation, continuation-in-part and reissue of said application; and the entire right, title and interest in and to said invention throughout the world, including the right to apply for patents and inventor certificates in respect thereof and to claim priority pursuant to rights accorded ASSIGNOR under the terms of the Paris International Convention and all other available international conventions and treaties; and the entire right, title and interest in and to any and all patents, patents of addition, utility models, patents of importation, revalidation patents and inventor certificates which may be granted throughout the world in respect of said invention.

ALSO, ASSIGNOR hereby agrees to execute any documents that legally may be required in connection with the filing, prosecution and maintenance of said application or any other patent application(s) or inventor certificate(s) in the United States and in foreign countries for said invention, including additional documents that may be required to affirm the rights of ASSIGNEE in and to said invention, all without further consideration. ASSIGNOR also agrees, without further consideration and at ASSIGNEE's expense, to identify and communicate to ASSIGNEE at ASSIGNEE'S request documents and information concerning the invention that are within ASSIGNOR'S possession or control, and to provide further assurances and testimony on behalf of ASSIGNEE that lawfully may be required of ASSIGNOR in respect of the prosecution, maintenance and defense of any patent application or patent encompassed within the terms of this instrument. ASSIGNOR'S obligations under this instrument shall extend to Assignor's heirs, executors, administrators and other legal representatives.

ASSIGNOR hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all United States Letters Patent referred to above to ASSIGNEE of the entire right, title and interest in and to the same, for ASSIGNEE'S sole use and behalf, and for the use and behalf of ASSIGNEE'S legal representatives and successors, to the full end of the term for which such Letters Patent may be granted, as fully and entirely as the same would have been held by ASSIGNOR had this assignment and sale not been made.

Name SHEN, GENG-SHIN

Geng-Shin Shen  
Signature

Address

Jun 22 2007  
Date

No.1, R&D Rd.1, Science-Based Industrial Park,  
Hsinchu, Taiwan, R.O.C.

Name TU, WU-CHANG

Tu Wu-chang  
Signature

Address

6/22/2007  
Date

No.1, R&D Rd.1, Science-Based Industrial Park,  
Hsinchu, Taiwan, R.O.C